

S/N 09/650,566

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Kishore K. Chakravorty et al.

Examiner: Thanh S Phan

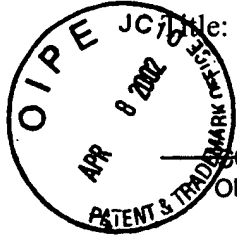
Serial No.: 09/650,566

Group Art Unit: 2841

Filed: August 30, 2000

Docket: 884.315US1

Title: ELECTRONIC ASSEMBLY COMPRISING CERAMIC/ORGANIC HYBRID
SUBSTRATE WITH EMBEDDED CAPACITORS AND METHODS OF
MANUFACTURE



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RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
Washington, D.C. 20231

In response to the Restriction Requirement mailed February 27, 2002, Applicants elect, without traverse, Group I (claims 1-10 and 28-30). Applicants cancel remaining claims 11-27 without prejudice or disclaimer, and Applicants reserve the right to reintroduce them in one or more divisional applications at a later date.

Applicants are filing a Preliminary Amendment with this Response.

The Examiner is invited to contact Applicants' Representative Walter W. Nielsen at 602/298-8920 or the below signed attorney if there are any questions regarding this Response or if prosecution of this application may be assisted thereby.

Respectfully submitted,

KISHORE K. CHAKRAVORTY ET AL.

By their Representatives,

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Date March 27, 2002

By Ann M. McCrackin

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 27 day of March, 2002.

Jane E. Brockschink
Name

Jane E. Brockschink
Signature

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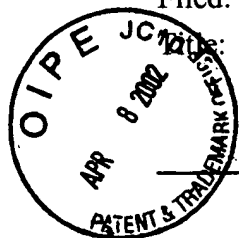
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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Before taking up the above-identified application for substantive examination, please enter the following amendments.

IN THE CLAIMS

Please cancel claims 11-27 without prejudice.

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claims 11-27, and the amendment of originally filed claims 1, 4, 6, 28, and 29. The specific amendments to individual claims are detailed in the following marked up set of claims.

1. (Amended) A multilayer substrate to mount [for mounting] a die comprising:

a ceramic portion comprising an embedded capacitor having first and second terminals;
a first plurality of lands on a first surface thereof, including a first land coupled to the first terminal and a second land coupled to the second terminal, wherein the first and second lands are positioned to couple [be coupled] to corresponding power supply nodes of the die; and
an organic portion comprising a plurality of conductors, including a first conductor coupling the first land to the first terminal and a second conductor coupling the second land to the second terminal.

4. (Amended) The multilayer substrate recited in claim 2, wherein the first plurality of lands further comprises a fifth land positioned to couple [be coupled] to a corresponding signal node of the die, and wherein the second plurality of lands comprises a sixth land coupled to the fifth land via a conductive path that comprises one of the plurality of conductors.

6. (Amended) The multilayer substrate recited in claim 2, wherein the third and fourth lands are positioned to couple [be coupled] to corresponding power supply nodes of an additional substrate